



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N: CL05A105KQ3LNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1µF, 6.3V, ±10%, X5R, 0402

## A. Samsung Part Number

<u>CL</u> <u>05</u> <u>A</u> <u>105</u> <u>K</u> <u>Q</u> <u>3</u> <u>L</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	0402 (inch code)	L: 1.0	± 0.05	mm	W:	$0.5 \pm 0.05$	mm
			Thickness division			Low profile		
3	Dielectric	X5R		Inner electrode		Ni		
4	Capacitance	<b>1</b> μF		Termina	ation		Cu	
⑤	Capacitance	±10 %		Plating			Sn 100%	(Pb Free)
	tolerance		9	Product	t		Normal	
6	Rated Voltage	6.3 V	10	Special		Reserved for future use		
7	Thickness	$0.3 \pm 0.03 \text{ mm}$	11)	Packaging		Cardboard Type, 7" reel		

## **B. Samsung Reliability Test and Judgement condition**

	Judgement	Test condition				
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms				
Tan δ (DF)	0.1 max.					
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X5R					
characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5°C, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Judgement	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR : 12.5MΩ·μF or Over					
High Temperature	Capacitance change: within ±12.5%	With 100% of the rated voltage				
Resistance	Tan δ 0.125 max	Max. operating temperature				
	IR : 25MΩ·μF or Over	1000+48/-0hrs				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 ℃				
		→ Max. operating temperature → 25°C				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.